

General Description

The GreenMOS® high voltage MOSFET utilizes charge balance technology to achieve outstanding low on-resistance and lower gate charge. It is engineered to minimize conduction loss, provide superior switching performance and robust avalanche capability.

The GreenMOS® SuperSi series is based on Oriental Semiconductor's unique device design to achieve extremely fast switching characteristics. It is the perfect replacement for the Gallium Nitride (GaN) device in high frequency operations with better ruggedness and cost. It is targeted to meet the most aggressive efficiency standards of power supply systems by pushing both performance and power density to extreme limits.

Features

- Low $R_{DS(ON)}$ & FOM
- Extremely low switching loss
- Excellent stability and uniformity
- Easy to design in



Applications

- PD charger
- Large screen display
- Telecom power
- Server power

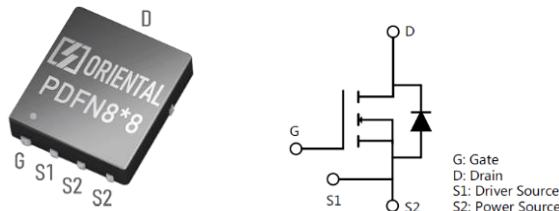
Key Performance Parameters

Parameter	Value	Unit
$V_{DS, min} @ T_{j(max)}$	700	V
$I_D, pulse$	36	A
$R_{DS(ON), max} @ V_{GS}=10V$	340	mΩ
Q_g	9.6	nC

Marking Information

Product Name	Package	Marking
OSS65R340JF	PDFN8*8	OSS65R340J

Package & Pin Information



Absolute Maximum Ratings at $T_j=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-source voltage	V_{DS}	650	V
Gate-source voltage	V_{GS}	± 30	V
Continuous drain current ¹⁾ , $T_C=25^\circ\text{C}$	I_D	12	A
Continuous drain current ¹⁾ , $T_C=100^\circ\text{C}$		7.6	
Pulsed drain current ²⁾ , $T_C=25^\circ\text{C}$	$I_{D,\text{pulse}}$	36	A
Continuous diode forward current ¹⁾ , $T_C=25^\circ\text{C}$	I_S	12	A
Diode pulsed current ²⁾ , $T_C=25^\circ\text{C}$	$I_{S,\text{pulse}}$	36	A
Power dissipation ³⁾ , $T_C=25^\circ\text{C}$	P_D	83	W
Single pulsed avalanche energy ⁵⁾	E_{AS}	200	mJ
MOSFET dv/dt ruggedness, $V_{DS}=0\ldots 480\text{ V}$	dv/dt	50	V/ns
Reverse diode dv/dt, $V_{DS}=0\ldots 480\text{ V}$, $I_{SD} \leq I_D$	dv/dt	15	V/ns
Operation and storage temperature	T_{stg}, T_j	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal resistance, junction-case	$R_{\theta JC}$	1.5	°C/W
Thermal resistance, junction-ambient ⁴⁾	$R_{\theta JA}$	62	°C/W

Electrical Characteristics at $T_j=25^\circ\text{C}$ unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	BV_{DSS}	650			V	$V_{GS}=0\text{ V}$, $I_D=250\text{ }\mu\text{A}$
		700				$V_{GS}=0\text{ V}$, $I_D=250\text{ }\mu\text{A}$, $T_j=150^\circ\text{C}$
Gate threshold voltage	$V_{GS(\text{th})}$	2.9		3.9	V	$V_{DS}=V_{GS}$, $I_D=250\text{ }\mu\text{A}$
Drain-source on-state resistance	$R_{DS(\text{ON})}$		0.30	0.34	Ω	$V_{GS}=10\text{ V}$, $I_D=6\text{ A}$
			0.73			$V_{GS}=10\text{ V}$, $I_D=6\text{ A}$, $T_j=150^\circ\text{C}$
Gate-source leakage current	I_{GSS}			100	nA	$V_{GS}=30\text{ V}$
				-100		$V_{GS}=-30\text{ V}$
Drain-source leakage current	I_{DSS}			1	μA	$V_{DS}=650\text{ V}$, $V_{GS}=0\text{ V}$

Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	C _{iss}		443.5		pF	V _{GS} =0 V, V _{DS} =50 V, f=100 KHz
Output capacitance	C _{oss}		59.6		pF	
Reverse transfer capacitance	C _{rss}		1.7		pF	
Turn-on delay time	t _{d(on)}		22.4		ns	V _{GS} =10 V, V _{DS} =400 V, R _G =2 Ω, I _D =6 A
Rise time	t _r		17.5		ns	
Turn-off delay time	t _{d(off)}		40.3		ns	
Fall time	t _f		7.2		ns	

Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	Q _g		9.6		nC	V _{GS} =10 V, V _{DS} =400 V, I _D =6 A
Gate-source charge	Q _{gs}		2.2		nC	
Gate-drain charge	Q _{gd}		4.5		nC	
Gate plateau voltage	V _{plateau}		6.5		V	

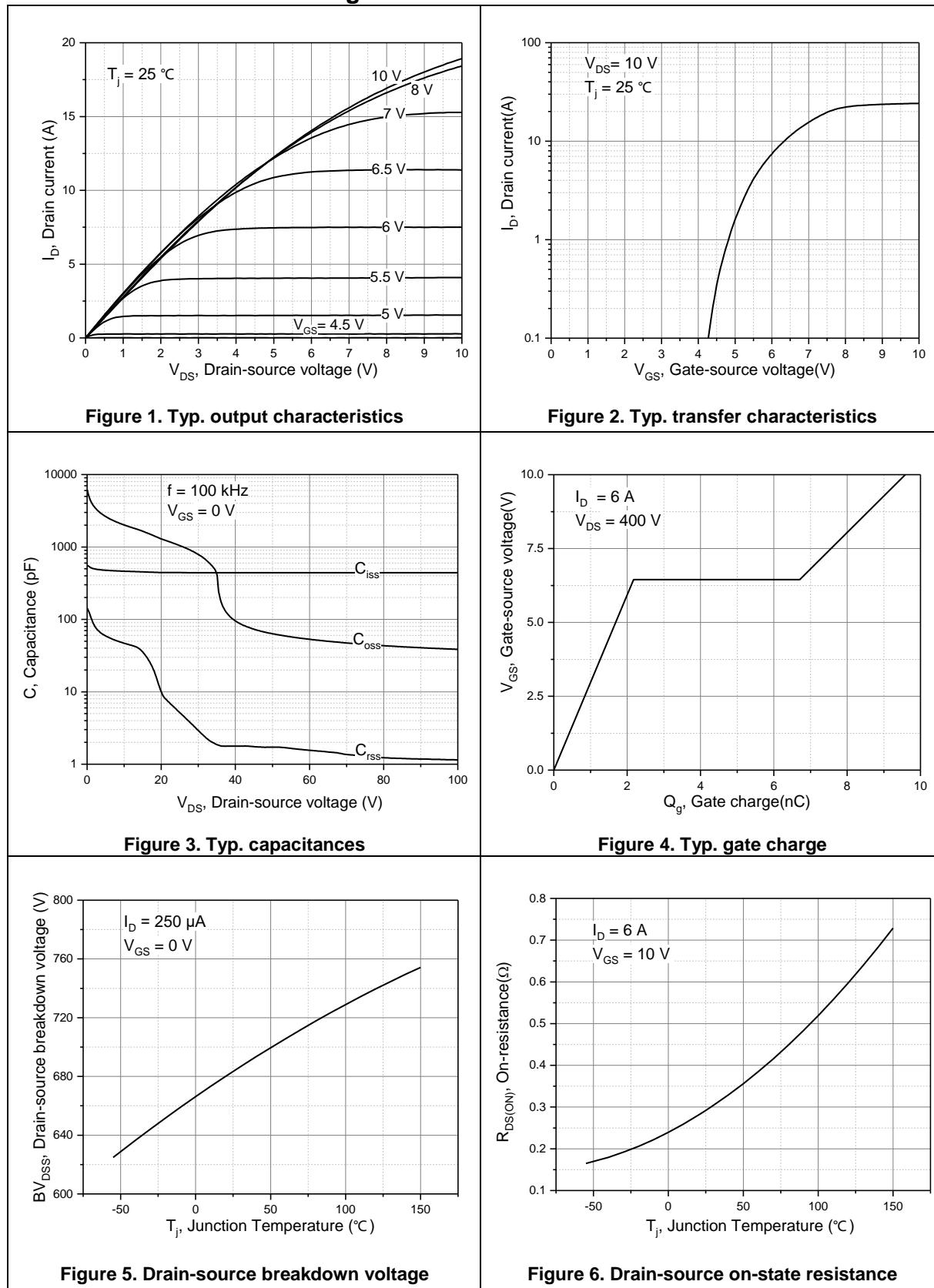
Body Diode Characteristics

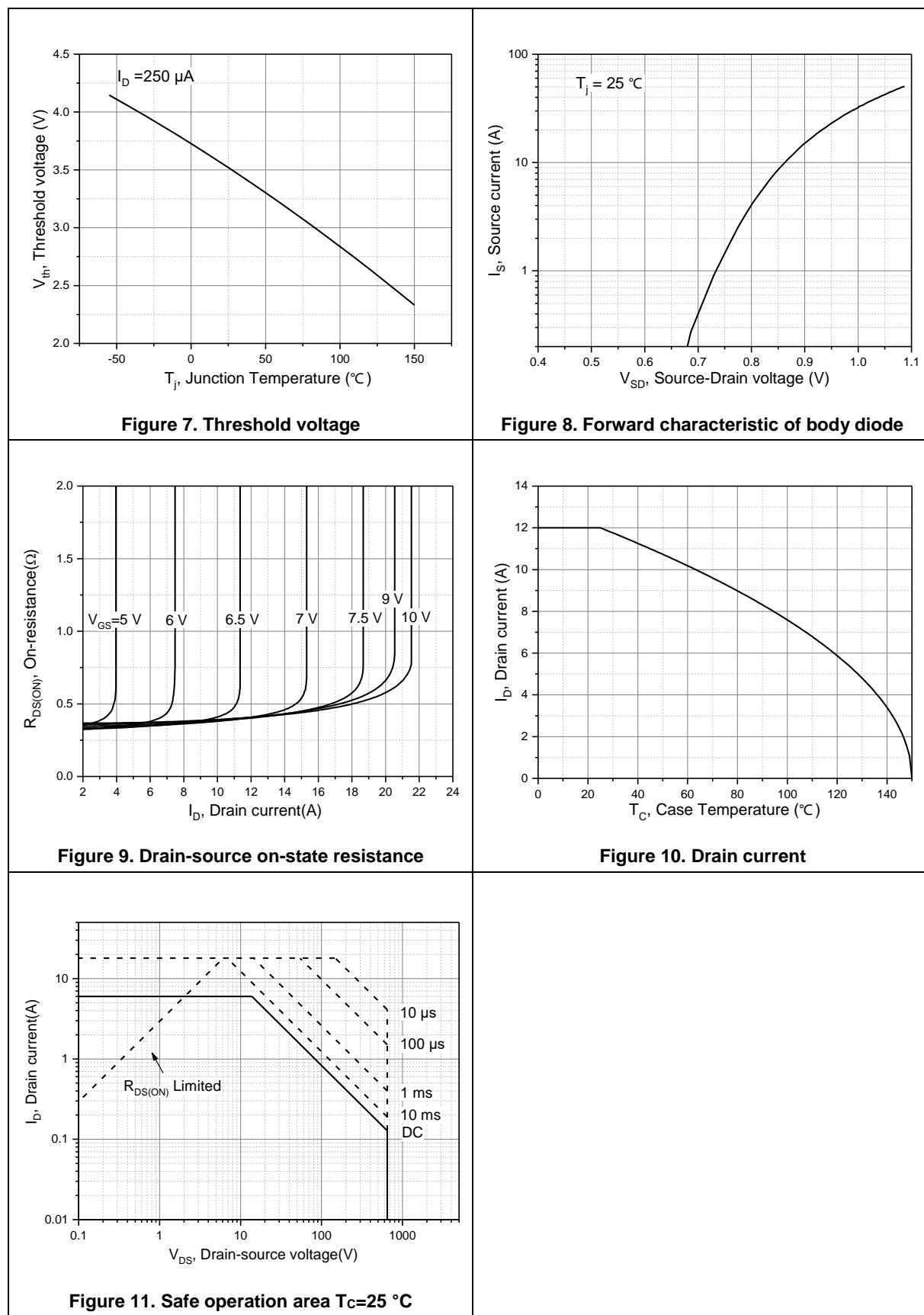
Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode forward voltage	V _{SD}			1.3	V	I _S =12 A, V _{GS} =0 V
Reverse recovery time	t _{rr}		236.5		ns	V _R =400 V, I _S =6 A, di/dt=100 A/μs
Reverse recovery charge	Q _{rr}		2.2		μC	
Peak reverse recovery current	I _{rrm}		19.1		A	

Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of R_{θJA} is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T_a=25 °C.
- 5) V_{DD}=100 V, V_{GS}=10 V, L=60 mH, starting T_j=25 °C.

Electrical Characteristics Diagrams





Test circuits and waveforms



Figure 1. Gate charge test circuit & waveform

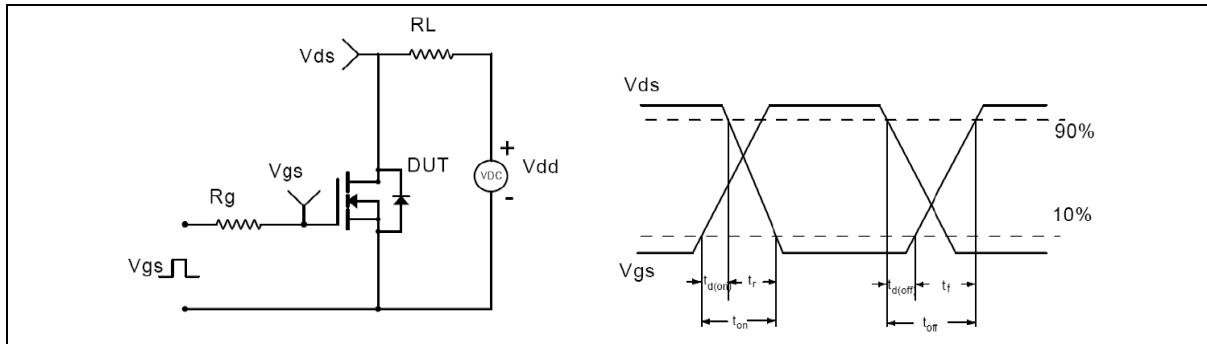


Figure 2. Switching time test circuit & waveforms

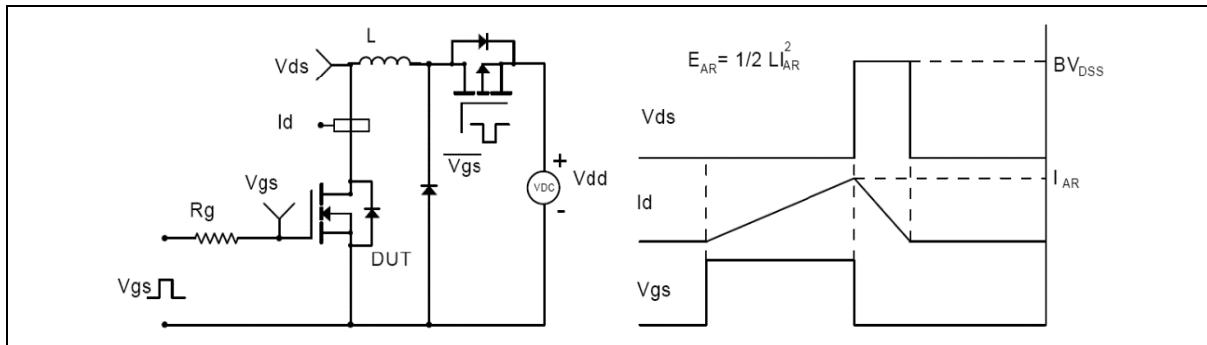


Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms

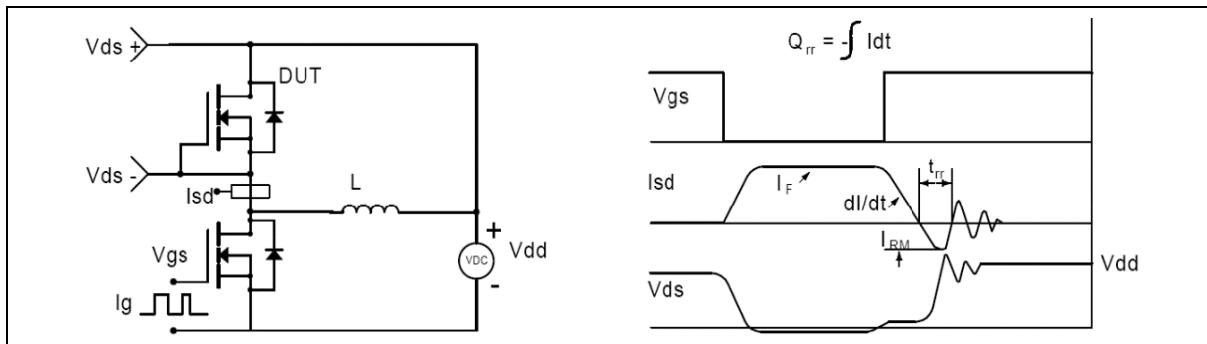
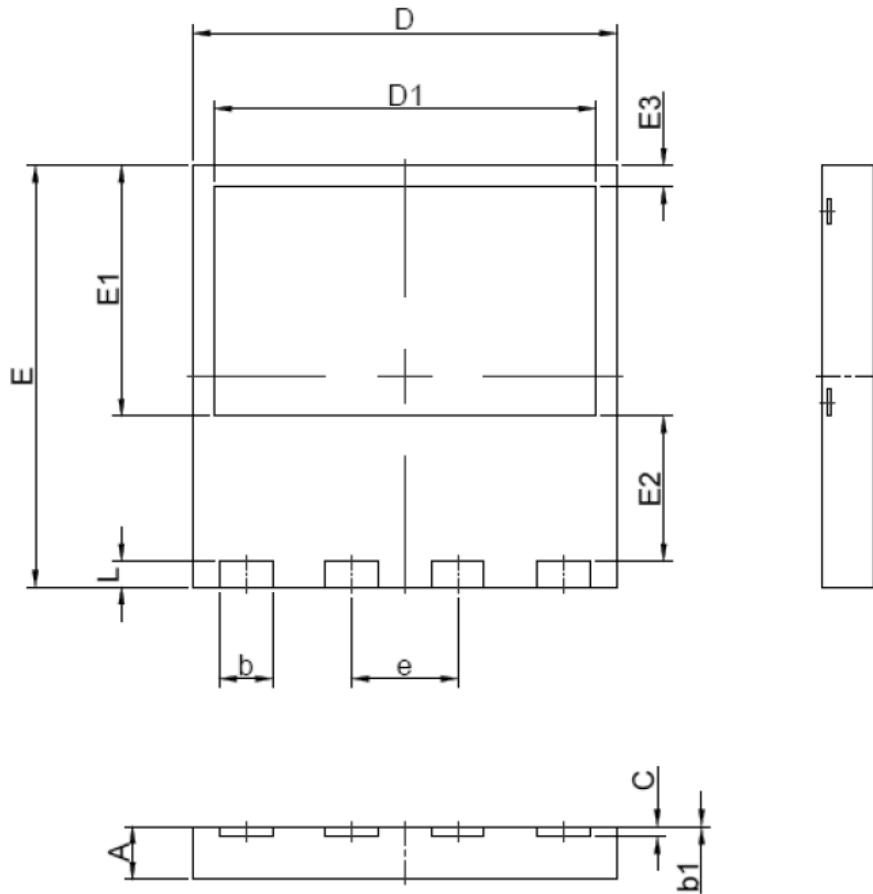


Figure 4. Diode reverse recovery test circuit & waveforms

Package Information



Symbol	mm		
	Min	Nom	Max
A	0.90	1.00	1.10
b	0.90	1.00	1.10
b1	0.00	0.02	0.05
C	0.2REF		
D	7.90	8.00	8.10
D1	7.10	7.20	7.30
E	7.90	8.00	8.10
E1	4.65	4.75	4.85
E2	2.65	2.75	2.85
E3	0.30	0.40	0.50
e	2.0BSC		
L	0.40	0.50	0.60

Version 1: PDFN8*8-L package outline dimension

Ordering Information

Package Type	Units/Reel	Reels/Inner Box	Units/Inner Box	Inner Boxes/Carton Box	Units/Carton Box
PDFN8*8-L	2500	1	2500	10	25000

Product Information

Product	Package	Pb Free	RoHS	Halogen Free
OSS65R340JF	PDFN8*8	yes	yes	yes

Legal Disclaimer

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